Overview

HP ProBook x360 435 G8 Notebook PC



- 1. Internal Microphones
- 2. Webcam LED
- 3. Webcam and IR Camera (Optional)
- 4. HP Privacy Camera
- 5. IR Camera LED (Optional)
- 6. Clickpad

Left

- 7. World-facing Camera (Optional)
- 8. World-facing Camera LED (Optional)
- 9. Vents
- 10. SuperSpeed USB Type-A 5 Gbps signaling rate charging Port
- 11. Nano Security Lock Slot (Lock Sold Separately)



Overview



- 1. Power Button
- 2. Power Connector
- **3.** SuperSpeed USB Type-C[®] 10Gbps signaling rate (USB Power Delivery, DisplayPort[™] 1.4)
- 4. SuperSpeed USB Type-A 5 Gbps signaling rate Port
- Right
- 5. HDMI 1.4b Port (Cable not included)
- 6. Audio Combo Jack
- 7. MicroSD Card reader (Select Models)
- 8. Touch Fingerprint Sensor (Select models)

Overview

AT A GLANCE

- Preinstalled with Windows 10 versions or FreeDOS
- A stylish and professional convertible adapts with versatile use modes from traditional laptop to tablet, stand and tent that enables to create, present and collaborate
- Sleek and durable anodized aluminum top cover and keyboard deck
- Choice of AMD Ryzen™ 5000 series mobile processors
- Integrated AMD Radeon™ Graphics
- Display include your choice of 33.8 cm (13.3") diagonal IPS Wide Viewing Angle, FHD, touch screen with Corning[®] Gorilla[®] Glass 5
- Commercial-grade security features including HP Sure Start, HP Sure Sense, HP Client Security, HP Sure Click, Camera Privacy Shutter and optional HP Sure View
- Captures the world around with an optional world facing- camera in the keyboard¹
- Supports wireless LAN options for connectivity on the go including gigabit data rate Wi-Fi® 6¹
- Supports fast charging (50% in 30 minutes) with no impact on battery recharge cycles
- Undergoes MIL-STD 810H tests²

1. Sold separately or as an optional feature.

2. MIL STD 810H testing is not intended to demonstrate fitness for U.S. Department of Defense contract requirements or formilitary use. Test results are not a guarantee of future performance under these test conditions. Accidental damage requires an optional HP Accidental Damage Protection Care Pack.

NOTE: See important legal disclosures for all listed specs in their respective features sections.



PRODUCT NAME

HP ProBook x360 435 G8 Notebook PC

OPERATING SYSTEM

Windows10 Pro 64 – HP recommends Windows 10 Pro ¹
Windows10 Pro 64 (National Academic License) ²
Windows10 Home 64 ¹
Windows10 Home Single Language 64 ¹
Windows 10 Pro (Windows 10 Enterprise available with a Volume Licensing Agreement) ¹
Windows10 Enterprise 64 (Web Support) ¹
FreeDOS

1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com/.

2. Some devices for academic use will automatically be updated to Windows 10 Pro Education with the Windows 10 Anniversary Update. Features vary; see https://aka.ms/ProEducation for Windows 10 Pro Education feature information. Note: HP tested Windows 10, version 1909 on this platform. For testing information on newer versions of Windows 10, please see https://support.hp.com/document/c05195282.

PROCESSORS

AMD Ryzen™ 3 5400U with Radeon™ Graphics (2.6 GHz base clock, up to 4.0 GHz max boost clock, 8 MB L3 cache, 4 cores) ^{3,4,5,6}
AMD Ryzen™ 3 Pro 5450U with Radeon™ Graphics (2.6 GHz base clock, up to 4.0 GHz max boost clock, 8 MB L3 cache, 4 cores) ^{3,4,5,6} Available April 2021
AMD Ryzen™ 5 5600U with Radeon™ Graphics (2.3 GHz base clock, up to 4.2 GHz max boost clock, 16 MB L3 cache, 6 cores) ^{3,4,5,6}
AMD Ryzen™ 5 Pro 5650U with Radeon™ Graphics (2.3 GHz base clock, up to 4.2 GHz max boost clock, 16 MB L3 cache, 6 cores) ^{3,4,5,6}
AMD Ryzen™ 5 Pro 5650U with Radeon™ Graphics (2.3 GHz base clock, up to 4.2 GHz max boost clock, 16 MB L3 cache, 6 cores) ^{3,4,5,6}
AMD Ryzen™ 7 S800U with Radeon™ Graphics (1.9 GHz base clock, up to 4.4 GHz max boost clock, 16 MB L3 cache, 8 cores) ^{3,4,5,6}
AMD Ryzen™ 7 Pro 5850U with Radeon™ Graphics (1.9 GHz base clock, up to 4.4 GHz max boost clock, 16 MB L3 cache, 8 cores) ^{3,4,5,6}

Processor Family

AMD Ryzen[™] 3 processor⁶ AMD Ryzen[™] 5 processor⁶ AMD Ryzen[™] 7 processor⁶

3. Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode.



4. Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. AMD's numbering is not a measurement of clock speed.

5. AMD Max Burst frequency performance varies depending on hardware, software and overall system configuration.

6. In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on http://www.support.hp.com.

CHIPSET

Chipset is integrated with processor.

GRAPHICS

Integrated AMD Radeon[™] Graphics

Supports

Support HD decode, DX12, HDMI1.4b⁷, via HDMI up to 4K 30Hz

7. HDMI cable sold separately.

DISPLAY

Touch

33.8 cm (13.3") diagonal FHD UWVA eDP BrightView WLED-backlit touch screen with Corning[®] Gorilla[®] Glass 5, 250 nits, 45% NTSC with HD camera (1920 x 1080)^{8,9,10}

33.8 cm (13.3") diagonal FHD UWVA eDP BrightView WLED-backlit touch screen with Corning[®] Gorilla[®] Glass 5, 250 nits, 45% NTSC with HD + IR camera (1920 x 1080)^{8,9,10}

33.8 cm (13.3") diagonal FHD UWVA eDP + PSR BrightView WLED-backlit touch screen with Corning[®] Gorilla[®] Glass 5, Low Power, 400 nits, 72% NTSC with HD camera (1920 x 1080)^{8,9,10}

33.8 cm (13.3") diagonal FHD UWVA eDP + PSR BrightView WLED-backlit touch screen with Corning[®] Gorilla[®] Glass 5, Low Power, 400 nits, 72% NTSC with HD + IR camera (1920 x 1080)^{8,9,10}

HP Sure View Integrated Privacy Screen 33.8 cm (13.3") diagonal FHD UWVA eDP + PSR BrightView WLED-backlit touch screen with Corning[®] Gorilla[®] Glass 5, 1000 nits, 72% NTSC with HD camera (1920 x 1080) ^{8,9,10,11}

HP Sure View Integrated Privacy Screen 33.8 cm (13.3") diagonal FHD UWVA eDP + PSR BrightView WLED-backlit touch screen with Corning[®] Gorilla[®] Glass 5, 1000 nits, 72% NTSC with HD + IR camera (1920 x 1080) ^{8,910,11}

8. FHD/HD content required to view FHD/HD images.

9. Resolutions are dependent upon monitor capability, and resolution and color depth settings.

10. Actual brightness will be lower with touchscreen or Sure View.

11. HP Sure View integrated privacy screen is an optional feature that must be configured at purchase and is designed to function in landscape orientation.



STORAGE AND DRIVES

Primary M.2 Storage

128 GB PCIe[®] Gen3x4 NVMe[™] TLC Solid State Drive ¹² 256 GB PCIe[®] NVMe[™] Value Solid State Drive ¹² 512 GB PCIe[®] NVMe[™] Value Solid State Drive ¹² 512 GB PCIe[®] Gen3x4 NVMe[™] TLC Solid State Drive ¹² 1 TB PCIe[®] Gen3x4 NVMe[™] TLC Solid State Drive ¹²

12. For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.

MEMORY

Maximum Memory

32 GB DDR4-3200 SDRAM 13

Memory

32 GB DDR4 -3200 SDRAM (2 x 16GB) ¹³ 16 GB DDR4-3200 SDRAM (1 x 16 GB) ¹³ 16 GB DDR4-3200 SDRAM (2 x 8 GB) ¹³ 8 GB DDR4-3200 SDRAM (1 x 8 GB) ¹³ 8 GB DDR4-3200 SDRAM (2 x 4 GB) ¹³ 4 GB DDR4-3200 SDRAM (1 x 4 GB) ¹³

Memory Slots

2 SODIMM Both slots are customer accessible / upgradeable by IT or self-maintainers only. DDR4 PC4 SODIMMS, system runs at 3200 Supports Dual Channel Memory

13. Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.



NETWORKING/COMMUNICATIONS

WLAN

Realtek RTL8822CE 802.11ac (2x2) and Bluetooth[®] 5 Combo ¹⁴ Intel[®] Dual Band Wireless-AC 9260 802.11a/b/g/n/ac (2x2) Wi-Fi [®]and Bluetooth[®] 5 Combo, non-vPro[®] ¹⁴ Intel[®] AX200 Wi-Fi 6 (2x2) and Bluetooth[®] 5 Combo, non-vPro[®] ¹⁵

Miracast

Native Miracast Support ¹⁶

14. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 5 (802.11 ac) is backwards compatible with prior 802.11 specs.

15. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited.
 Wi-Fi 6 (802.11ax) is backwards compatible with prior 802.11 specs. Only available in countries where 802.11ax is supported.
 16. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming.

AUDIO/MULTIMEDIA

Audio

Integrated microphone (Dual Array) 2 Integrated stereo speakers

Speaker Power

2W/4ohm Per speaker

Camera

User-facing 720p HD camera ^{17,18} User-facing 720p HD + IR camera ^{17,18} World-facing 5MP auto-focus secondary camera ¹⁸

Sensors

Combo Chip (Accelerometer + Gyro) Magnetometer Hall Sensor

17. FHD/HD content required to view FHD/HD images.18. Sold separately or as an optional feature.



KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Keyboard

HP Premium Keyboard, spill resistant with DuraKeys and optional backlit ¹⁹

Pointing Device

Clickpad with multi-touch gesture support

Function Keys

F1 - Display Switching F2 - Blank or Privacy (with LED) F3 - Brightness Down F4 - Brightness Up F5 - Audio Mute F6 - Volume Down F7 - Volume Up F8 - Mic Mute F9 - Blank or Keyboard Backlit Toggle F10 - Insert F11 - Airplane Mode F12 - HP Programmable Key Power Button

Hidden Function Keys

Fn+R - Break Fn+S - Sys Rq Fn+C - Scroll Lock

19. Backlit keyboard is an optional feature.

SOFTWARE AND SECURITY

Preinstalled Software

BIOS HP BIOSphere Gen6²⁰ BIOS Update via Network HP Secure Erase²¹ Absolute Persistence Module²² HP Wake on WLAN

Software

HP Connection Optimizer²³ HP Hotkey Support HP Support Assistant²⁴ HP Noise Cancellation Software Buy Office (Sold separately) Microsoft Defender²⁵ HP Smart Support ⁴⁵



Manageability Features

HP Driver Packs (download)²⁶ HP Client Catalog (download) HP Manageability Integration Kit Gen4(download)²⁷ HP Image Assistant (download)

Security Management

TPM 2.0 Embedded Security Chip (Common Criteria EAL4+ Certified) (FIPS 140-2 Level 2 Certified) USB enable/disable (via BIOS) Setup password (via BIOS) Support for chassis padlocks and cable lock devices HP Sure Click²⁸ HP Sure Sense²⁹ HP Sure Start Gen7 ³⁰ HP Sure View Gen3³¹ HP Sure Admin³² HP Wolf Pro Security Edition³³ HP Fingerprint Sensor (Select models) ³⁴

20. HP BIOSphere Gen6 is available on select HP Pro and Elite PCs. Features may vary depending on the platform and configurations.

21. HP Secure Erase for the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel® Optane™.

22. Absolute firmware module is shipped turned off and can only be activated with the purchase a license subscription and full activation of the software agent. License subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. Certain conditions apply. For full details visit: https://www.absolute.com/about/legal/agreements/absolute/

23. HP Connection Optimizer requires Windows 10.

24. HP Support Assistant requires Windows and Internet access.

25. Windows Defender Opt in and internet connection required for updates.

26. HP Driver Packs not preinstalled, however available for download at http://www.hp.com/go/clientmanagement.

27. HP Manageability Integration Kit can be downloaded from

http://www8.hp.com/us/en/ads/clientmanagement/overview.html.

28. HP Sure Click requires Windows 10 Pro or Enterprise. See https://bit.ly/2PrLT6A_SureClick for complete details.

29.HP Sure Sense is available on select HP PCs and is not available with Windows10 Home.

30. HP Sure Start Gen6 is available on select HP PCs and requires Windows 10.

31. HP Sure View Gen3 integrated privacy screen is an optional feature that must be configured at purchase and is designed to function in landscape orientation.

32. HP Sure Admin requires Windows 10, HP BIOS, HP Manageability Integration Kit from

http://www.hp.com/go/clientmanagement and HP Sure Admin Local Access Authenticator smartphone app from the Android or Apple store.

33. HP Wolf Pro Security Edition (including HP Sure Click Pro and HP Sure Sense Pro) is available preloaded on select SKUs and, depending on the HP product purchased, includes a paid 1-year or 3-year license. The HP Wolf Pro Security Edition software is licensed under the license terms of the HP Wolf Security Software - End-User license Agreement (EULA) that can be found at: https://support.hp.com/us-en/document/ish_3875769-3873014-16 as that EULA is modified by the following: "7. Term. Unless otherwise terminated earlier pursuant to the terms contained in this EULA, the license for the HP Wolf Pro Security Edition (HP Sure Sense Pro and HP Sure Click Pro) is effective upon activation and will continue for either a twelve

(12) month or thirty-six (36) month license term ("Initial Term"). At the end of the Initial Term you may either (a) purchase a



renewal license for the HP Wolf Pro Security Edition from HP.com, HP Sales or an HP Channel Partner, or (b) continue using the standard versions of HP Sure Click and HP Sure Sense at no additional cost with no future software updates or HP Support.

34. HP Fingerprint sensor is an optional feature that must be configured at purchase.

45. HP Smart Support is available to commercial customers through your HP Service Representative and HP Factory Configuration Services; or it can be downloaded at: http://www.hp.com/smart-support. HP Smart Support automatically collects the telemetry necessary upon initial boot of the product to deliver device-level configuration data and health insights.

POWER

Power Supply

HP Smart 65 W External AC power adapter ³⁵ HP Smart 65 W EM External AC power adapter ³⁵ HP Smart 65 W USB Type-C adapter ³⁵ HP Smart 45 W External AC power adapter ³⁵ HP Smart 45 W USB Type-C adapter ³⁵

Power Cord

3-wire plug - 1m ³⁵ 2-wire plug - 1m ³⁵

Primary Battery

HP Long Life 3-cell, 45 Wh Li-ion polymer ^{36,37} Support HP Fast Charge (Up to 50% in 30 minutes with 65W AC Adapter)³⁸

Battery life

Up to 17 hours ³⁹

35. Availability may vary by country.

36. Battery is internal and not replaceable by customer. Serviceable by warranty.

37. Actual battery Watt-hours (Wh) will vary from design capacity. Battery capacity will naturally decrease with shelf life, time, usage, environment, temperature, system configuration, loaded apps, features, power management settings and other factors.

38. Supports HP Fast Charge with 65W AC Adapter. Recharges the battery up to 50% within 30 minutes when the system is off or in standby mode. Power adapter with a minimum capacity of 65 watts is required. After charging has reached 50% capacity, charging will return to normal. Charging time may vary +/-10% due to System tolerance.

39. Windows 10 MM18 battery life will vary depending on various factors including product model, configuration, loaded applications, features, use, wireless functionality, and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See www.bapco.com for additional details.



WEIGHTS & DIMENSIONS

Weight

Starting at 3.19 lb (1.45 kg)⁴⁰

Dimensions (w x d x h) 12.15 x 8.78 x 0.71 in 30.85 x 22.295 x 1.795 cm

40. Weight will vary by configuration.

PORTS/SLOTS

Ports

SuperSpeed USB Type-C[®] 10Gbps signaling rate (USB Power Delivery, DisplayPort[™] 1.4)
 SuperSpeed USB Type-A 5 Gbps signaling rate (1 charging port)
 HDMI 1.4b⁴¹
 Headphone/microphone combo jack
 AC power

Expansion Slots 1 microSD Supports SD, SDHC, SDXC

41. HDMI cable sold separately.



SERVICE AND SUPPORT

1-year and 3-year limited warranties and 90-day software limited warranty options depending on country. Batteries have a default one-year limited warranty except for HP Long Life batteries which will follow the one or three year warranty of the platform. Refer to http://www.hp.com/support/batterywarranty/ for additional battery information. On-site service and extended coverage is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/cpc.⁴²

42. HP Care Packs are sold separately. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit http://www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.



SYSTEM UNIT

Chand Alana Davan		101/
Stand-Alone Power Requirements (AC Power)	Nominal Operating Voltage	19 V
	Average Operating Power	5.71 w
	Integrated Graphics	AMD
	Max Operating Power	UMA < 45W
Temperature	Operating	41° to 95° F (5° to 35° C)
	Non-operating	-4° to 140° F (-20° to 60° C)
Relative Humidity	Operating	10% to 90%, non-condensing
	Non-operating	5% to 95%, 101.6° F (38.7° C) maximum wet bulb temperature
Shock	Operating	40 G, 2 ms, half-sine
	Non-operating	200 G, 2 ms, half-sine
Random Vibration	Operating	0.75 grms
	Non-operating	1.50 grms
Altitude (unpressurized)	Operating	-50 to 10,000 ft (-15.24 to 3,048 m)
	Non-operating	-50 to 10,000 ft (-15.24 to 3,048 m)
Planned Industry Standard	UL	Yes
Certifications	CSA	Yes
	FCC Compliance	Yes
	ENERGY STAR [®]	Yes, Select models ⁴³
	EPEAT [®]	Yes, Gold in U.S. ⁴⁴
	ICES	Yes
	Australia	Yes
	NZ A-Tick Compliance	Yes
	כככ	Yes
	Japan VCCI Compliance	Yes
	KC	Yes
	BSMI	Yes
	CE Marking Compliance	Yes
	BNCI or BELUS	Yes
	CIT	Yes
	EAC	Yes
	Saudi Arabian Compliance (ICCP)	Yes
	SABS	Yes
	UKRSERTCOMPUTER	Yes

43. Configurations of the HP ProBook x360 435 G7 G8 that are ENERGY STAR[®] qualified are identified as HP ProBook x360 435 G8 ENERGY STAR on HP websites and on http://www.energystar.gov.



44. Based on US EPEAT[®] registration according to IEEE 1680.1-2018 EPEAT[®]. EPEAT[®] status varies by country. Visit www.epeat.net for more information.

DISPLAYS

Note: All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

1. Actual brightness will be lower with touchscreen or Sure View.

Panel LCD 13.3 inch diagonal FHD (1920 x 1080) Anti-Glare	Outline Dimensions (W x H x D)	300.56 x 187.77 mm (max) (w/ PCB & w/o bracket)
WLED UWVA 45% NTSC 250	Active Area	293.76 x 165.24 mm (typ.)
nits eDP 1.2 w/o PSR slim	Weight	260 g (max)
	Diagonal Size	13.3 inch
	Thickness	3.0 mm (max)
	Interface	eDP 1.2 (2 lane)
	Surface Treatment	BrightView Glass
	Touch Enabled	Yes
	Contrast Ratio	600:1 (typ.)
	Refresh Rate	60 Hz
	Brightness ¹	250nits (typ.)
	Pixel Resolution	1920 x 1080 (FHD)
	Format of LCD Pixel Arrangement	RGB
	Backlight	LED
	Color Gamut Coverage	45% NTSC
	Color Depth	6 bits
	Viewing Angle	UWVA 85/85/85/85



Panel LCD 13.3 inch diagonal

FHD (1920 x 1080) Anti-Glare

WLED UWVA 72% NTSC 400

nits eDP 1.4+PSR2 ultraslim

Technical Specifications

Outline Dimensions (W x H x D) 299.06 x 185.54 mm (max) **Active Area** 293.76 x 165.24 mm (typ.) Weight 170 g (max) **Diagonal Size** 13 inch Thickness 2.0 mm (max) Interface eDP 1.4 + PSR2 (2 lane) Surface Treatment **BrightView Glass Touch Enabled** Yes **Contrast Ratio** 1200:1 (typ.) **Refresh Rate** 60 Hz **Brightness**¹ 400 nits **Pixel Resolution** 1920 x 1080 (FHD) **Format of LCD Pixel Arrangement** RGB Backlight LED **Color Gamut Coverage** 72% NTSC **Color Depth** 8 bits **Viewing Angle** UWVA 85/85/85/85



Panel LCD 13.3 inch diagonal FHD (1920 x 1080) BrightView	Outline Dimensions (W x H x D)	298.76 x 186.04 mm (typ.)
WLED UWVA 72% NTSC 1000	Active Area	293.76 x 165.24 mm (typ.)
nits eDP 1.4+PSR2 flat Privacy NWBZ	Weight	255 g (max)
	Diagonal Size	13.3 inch
	Thickness	3.0 mm (max)
	Interface	eDP 1.4 + PSR2
	Surface Treatment	BrightView Glass
	Touch Enabled	Yes
	Contrast Ratio	2000:1 (typ.)
	Refresh Rate	60 Hz
	Brightness ¹	1000 nits
	Pixel Resolution	1920 x 1080(FHD)
	Format of LCD Pixel Arrangement	RGB
	Backlight	LED
	Color Gamut Coverage	72% NTSC
	Color Depth	8 bit
	Viewing Angle	UWVA 85/85/85/85



STORAGE

Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is

reserved for system recovery software.

128 GB 2280 M2 PCIe NVMe	Form Factor	M.2 2280
TLC Solid State Drive	Capacity	128 GB
	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	PCIe NVMe
	Maximum Sequential Read	1300~2047MB/s
	Maximum Sequential Write	800~1200MB/s
	Logical Blocks	250,069,680
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	ATA Security; DIPM; TRIM; DEVSLP

256 GB 2280 PCIe NVMe	Form Factor	M.2 2280
Value Solid State Drive	Capacity	256 GB
	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	PCIe NVMe
	Maximum Sequential Read	Around 1500 ~ 1700 MB/s
	Maximum Sequential Write	Around 780 ~ 1300 MB/s
	Logical Blocks	500118192
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	ATA Security; TRIM; L1.2



SSD 512 GB 2280 M2	Form Factor	M.2 2280
PCIe-3x4 SS NVMe TLC	Capacity	512 GB
	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	PCIe NVMe Gen3X4
	Maximum Sequential Read	Around 2700 ~ 3400 MB/s
	Maximum Sequential Write	Around 1390 ~ 2956 MB/s
	Logical Blocks	1000215215
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	ATA Security; TRIM; L1.2
SSD 512 GB 2280 PCIe	Form Factor	M.2 2280
NVMe Value	Capacity	512 GB
	NAND Type	TLC/QLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	PCIe NVMe
	Maximum Sequential Read	Around 1500 ~ 1700 MB/s
	Maximum Sequential Write	Around 860 ~ 1500 MB/s
	Logical Blocks	1000215215
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	ATA Security; TRIM; L1.2

SSD 1TB 2280 PCIe-3x4 NVMe	Form Factor	M.2 2280
Three Layer Cell single-sided	Capacity	1 TB
	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	PCIe NVMe Gen3X4
	Maximum Sequential Read	3100 ~ 3500 MB/s
	Maximum Sequential Write	2770 ~ 3037 MB/s
	Logical Blocks	2000409264
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	ATA Security; TRIM; L1.2



NETWORKING/COMMUNICATIONS

Realtek RTL8822CE 802.11ac 2x2 Wi-Fi® and Bluetooth® 5.0 ¹	Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11i IEEE 802.11i
		IEEE 802.11r IEEE 802.11v
	Interoperability	Wi-Fi certified
	Frequency Band	•802.11b/g/n 2.402 – 2.482 GHz •802.11a/n/ac 4.9 – 4.95 GHz (Japan) 5.15 – 5.25 GHz 5.25 – 5.35 GHz 5.47 – 5.725 GHz 5.825 – 5.850 GHz
	Data Rates	•802.11b: 1, 2, 5.5, 11 Mbps •802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11n: max 300Mbps •802.11ac : max 866.7Mbps
	Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
	Security ³	 IEEE 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification WPA3 certification IEEE 802.11i WAPI
	Network Architecture	Ad-hoc (Peer to Peer)
	Models	Infrastructure (Access Point Required)
	Roaming	IEEE 802.11 compliant roaming between access points

Output Power ²	 802.11b: +18.5dBm m 802.11g: +17.5dBm m 802.11a: +18.5dBm m 802.11n HT20(2.4GHz 802.11n HT40(2.4GHz) 802.11n HT20(5GHz): 802.11n HT40(5GHz): 802.11ac VHT80(5GHz) 	hinimum hinimum 2): +15.5dBm minimum 2): +14.5dBm minimum +15.5dBm minimum +14.5dBm minimum
Power Consumption	•Transmit mode: 2.0 W •Receive mode: 1.6 W •Idle mode (PSP)180 m •Idle mode: 50 mW (WL •Connected Standby/M •Radio disabled: 8 mW	AN unassociated)
Power Management	ACPI and PCI Express co 802.11 compliant powe	ompliant power management er saving mode
Receiver Sensitivity ⁴	802.11b, 1Mbps: -93.56 802.11b, 11Mbps: -84d 802.11a/g, 6Mbps: -86 802.11a/g, 54Mbps: -7 802.11n, MCS07: -67dE 802.11n, MCS15: -64dE 802.11ac, MCS0: -84dB 802.11ac, MCS9: -59dB	Bm maximum dBm maximum 2dBm maximum 8m maximum 8m maximum m maximum
Antenna type	enclosure Two embedded dual ba	with spatial diversity, mounted in the display nd 2.4/5 GHz antennas are provided to the card to mmunications and Bluetooth communications
Form Factor	PCI-Express M.2 MiniCa	rd with CNVi Interface
Dimensions	1. Type 2230: 2.3 x 22.0 2. Type 1216: 1.67 x 12	
Weight	1. Type 2230: 2.8 g 2. Type 126: 1.3 g	
Operating Voltage	3.3 v +/- 9%	
Temperature	Operating Non-operating	14° to 158° F (–10° to 70° C) –40° to 176° F (–40° to 80° C)
Humidity	Operating Non-operating	10% to 90% (non-condensing) 5% to 95% (non-condensing)
Altitude	Operating Non-operating	0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)



LED Activi	ty	LED Amber – Radio OFF LED OFF – Radio ON
HP Integrated Module with Bluetoot	h 4.0/4.1/4.2/5	.0 Wireless Technology
Bluetooth	Specification	4.0/4.1/4.2/5.0 Compliant
Frequency	/ Band	2402 to 2480 MHz
Number o Channels	f Available	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)
Signaling	Data Rate	Legacy: 3 Mbps signaling data rate ¹ 2.17 Mbps BLE: 1 Mbps signaling data rate ¹ 0.2 Mbps 1. Actual throughput may vary. Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit	Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR.
Power Cor	nsumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
Bluetooth Supported	Software I	Microsoft Windows Bluetooth Software
Power Ma	nagement	Microsoft Windows ACPI, and USB Bus Support
Certificat	ions	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Ma Certificati	nagement ions	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Supported		BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2



Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)

1. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 5 (802.11 ac) is backwards compatible with prior 802.11 specs.

2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.

3. Check latest software/driver release for updates on supported security features.

4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).



Intel® Wi-Fi 6 AX200 and	Wireless LAN Standards	IEEE 802.11a
Bluetooth [®] 5.0		IEEE 802.11b
(802.11ax 2 x 2, supporting gigabit data		IEEE 802.11g
rate) non-vPro ^{1,5}		IEEE 802.11n
		IEEE 802.11ac
		IEEE 802.11ax
		IEEE 802.11d
		IEEE 802.11e
		IEEE 802.11h
		IEEE 802.11i
		IEEE 802.11k
		IEEE 802.11r
		IEEE 802.11v
	Interoperability	Wi-Fi certified
	Frequency Band	•802.11b/g/n/ax
		2.402 – 2.482 GHz
		•802.11a/n/ac/ax
		4.9 – 4.95 GHz (Japan)
		5.15 – 5.25 GHz
		5.25 – 5.35 GHz
		5.47 – 5.725 GHz
		5.825 – 5.850 GHz
	Data Rates	•802.11b: 1, 2, 5.5, 11 Mbps
		•802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
		•802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
		•802.11n: max 300Mbps
		•802.11ac: 1733Mbps
		•802.11ax : max 2.4Gbps
	Modulation	Direct Sequence Spread Spectrum
		OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM
	Security ³	•IEEE 64 / 128 bit WEP encryption for a/b/g mode only
		•AES-CCMP: 128 bit in hardware
		•802.1x authentication
		•WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.
		•WPA2 certification •WPA3 certification
		•IEEE 802.11i
	Notice of Aughts stores	•IEEE 802.11i •WAPI
	Network Architecture Models	•IEEE 802.11i •WAPI Ad-hoc (Peer to Peer)
	Network Architecture Models Roaming	•IEEE 802.11i •WAPI

Output Power ²	• 802.11b : +17dBm minimum
	• 802.11g : +16dBm minimum
	• 802.11a : +17dBm minimum
	• 802.11n HT20(2.4GHz) : +14dBm minimum
	• 802.11n HT40(2.4GHz) : +13dBm minimum
	• 802.11n HT20(5GHz) : +14dBm minimum
	• 802.11n HT40(5GHz) : +13dBm minimum
	• 802.11ac VHT80(5GHz) : +10dBm minimum
	• 802.11ac VHT160(5GHz) : +10dBm minimum
	• 802.11ax HE40(2.4GHz) : +12dBm minimum
	• 802.11ax HE80(5GHz) : +10dBm minimum
	• 802.11ax HE160(5GHz) : +10dBm minimum
Power Consumption	•Transmit mode: 2.0 W
	•Receive mode: 1.6 W
	 Idle mode (PSP)180 mW (WLAN Associated)
	•Idle mode: 50 mW (WLAN unassociated)
	 Connected Standby/Modern Standby: 10mW
	•Radio disabled: 8 mW
Power Management	ACPI and PCI Express compliant power management
	802.11 compliant power saving mode
Receiver Sensitivity ⁴	802.11b, 1Mbps: -93.5dBm maximum
	802.11b, 11Mbps: -84dBm maximum
	802.11a/g, 6Mbps: -86dBm maximum
	802.11a/g, 54Mbps: -72dBm maximum
	802.11n, MCS07: -67dBm maximum
	802.11n, MCS15: -64dBm maximum
	802.11ac, MCS0(VHT80) : -84dBm maximum
	802.11ac, MCS9(VHT80) : -59dBm maximum
	802.11ac, MCS9(VHT160): -58.5dBm maximum
	802.11ax, MCS11(HE40): -57dBm maximum
	802.11ax, MCS11(HE80): -54dBm maximum
	802.11ax, MCS11(HE160): -53.5dBm maximum
Antenna type	High efficiency antenna with spatial diversity, mounted in the display
	enclosure
	Two embedded dual band 2.4/5 GHz antennas are provided to the card to
	support WLAN MIMO communications and Bluetooth communications
Form Factor	PCI-Express M.2 MiniCard
Dimensions	1. Type 2230: 2.3 x 22.0 x 30.0 mm
	2. Type 1216: 1.67 x 12.0 x 16.0 mm
Weight	1. Type 2230: 2.8 g
	2. Туре 126: 1.3 g



Technical Specifications

Operating Voltage	3.3 v +/- 9%	
Temperature	Operating Non-operating	14° to 158° F (–10° to 70° C) –40° to 176° F (–40° to 80° C)
Humidity	Operating Non-operating	10% to 90% (non-condensing) 5% to 95% (non-condensing)
Altitude	Operating Non-operating	0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio OFF LED OFF – Radio ON	

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1 Wireless Technology

Bluetooth Specification	4.0/4.1/4.2/5.0/5.1 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)
Signaling Data Rate	Legacy: 3 Mbps signaling data rate ¹ 2.17 Mbps BLE: 1 Mbps signaling data rate ¹ 0.2 Mbps 1. Actual throughput may vary.
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels
	Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 9.5 dBm for BR and EDR.
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
Bluetooth Software Supported	Microsoft Windows Bluetooth Software
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising



LE L2CAP Connection Oriented Channels **Train Nudging & Interlaced Scan** BT4.2 ESR08 Compliance LE Secure Connection-Basic/Full LE Privacy 1.2 – Link Layer Privacy LE Privacy 1.2 – Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP) BT5.1 ESR9/10 Compliance LE Advertisement Extensions **Channel Selection Algo** Limited High Duty Cycle Non-Connectable Advertising 2Mbps LE LE Long Range

Wireless access point and internet service required and sold separately. Availability of public wireless access points limited.
 Wi-Fi 6 is backwards compatible with prior 802.11 specs. Only available in countries where 802.11 ax is supported.
 The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of

transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.

3. Check latest software/driver release for updates on supported security features.

4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

5. Wi-Fi 5 or 6 is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels.



Intel® 9260 802.11a/b/g/n/ac (2 x 2) Wi-Fi® and Bluetooth® 5 Combo¹ (Non-vPro)	Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11h IEEE 802.11i IEEE 802.11r IEEE 802.11r
	Interoperability	Wi-Fi certified
	Frequency Band	•802.11b/g/n 2.402 – 2.482 GHz •802.11a/n/ac 4.9 – 4.95 GHz (Japan) 5.15 – 5.25 GHz 5.25 – 5.35 GHz 5.47 – 5.725 GHz 5.825 – 5.850 GHz
	Data Rates	•802.11b: 1, 2, 5.5, 11 Mbps •802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11n: max 300Mbps •802.11ac: max 1733Mbps
	Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
	Security ³	 IEEE 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification WPA3 certification IEEE 802.11i WAPI
	Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
	Roaming	IEEE 802.11 compliant roaming between access points
	Output Power ²	• 802.11b: +17dBm minimum

	• 802.11g: +16dBm mini		
	• 802.11a: +17dBm minimum		
	• 802.11n HT20(2.4GHz)		
	• 802.11n HT40(2.4GHz)		
	• 802.11n HT20(5GHz):		
	• 802.11n HT40(5GHz):		
	• 802.11ac VHT80(5GHz	•	
	• 802.11ac VHT160(5GH	z): + IVaBm minimum	
Power Consumption	•Transmit mode: 2.0 W		
	•Receive mode: 1.6 W		
	•Idle mode (PSP)180 mV		
	•Idle mode: 50 mW (WLA	· · · · · · · · · · · · · · · · · · ·	
	•Connected Standby/Mo	dern Standby: 10mW	
	•Radio disabled: 8 mW		
Power Management		npliant power management	
	802.11 compliant power	r saving mode	
Receiver Sensitivity ⁴	802.11b, 1Mbps: -93.5d	Bm maximum	
	802.11b, 11Mbps: -84dE	3m maximum	
	802.11a/g, 6Mbps: -86d	Bm maximum	
	802.11a/g, 54Mbps: -72	dBm maximum	
	802.11ac, MCS0(VHT80)	: -84dBm maximum	
	802.11ac, MCS9(VHT80)		
	802.11ac, MCS9(VHT160)): -58.5dBm maximum	
Antenna type	High efficiency antenna enclosure	with spatial diversity, mounted in the display	
	Two embedded dual ban	d 2.4/5 GHz antennas are provided to the card to	
	support WLAN MIMO communications and Bluetooth communications		
Form Factor	PCI-Express M.2 MiniCar	d	
Dimensions	1. Type 2230: 2.3 x 22.0 x 30.0 mm		
	2. Type 1216: 1.67 x 12.0 x 16.0 mm		
Weight	1. Type 2230: 2.8 g		
-	2. Type 126: 1.3 g		
Operating Voltage	3.3 v +/- 9%		
Temperature	Operating	14° to 158° F (–10° to 70° C)	
	Non-operating	-40° to 176° F (-40° to 80° C)	
Humidity	Operating	10% to 90% (non-condensing)	
-	Non-operating	5% to 95% (non-condensing)	
Altitude	Operating	0 to 10,000 ft (3,048 m)	
	Non-operating	0 to 50,000 ft (15,240 m)	
		0 to 50,000 it (15,230 iii)	



reennear Speerne		
	LED Activity	LED Amber – Radio OFF LED OFF – Radio ON
HP Integrated Module with	n Bluetooth 4.0/4.1/4.2/5	.0 Wireless Technology
	Bluetooth Specification	4.0/4.1/4.2/5.0 Compliant
	Frequency Band	2402 to 2480 MHz
	Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)
	Signaling Data Rate	Legacy: 3 Mbps signaling data rate ¹ 2.17 Mbps BLE: 1 Mbps signaling data rate ¹ 0.2 Mbps 1. Actual throughput may vary.
		Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
	Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR.
	Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
	Bluetooth Software Supported	Microsoft Windows Bluetooth Software
	Power Management	Microsoft Windows ACPI, and USB Bus Support
	Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
	Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
	Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX)



Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)

1. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 5 (802.11 ac) is backwards compatible with prior 802.11 specs.

2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.

3. Check latest software/driver release for updates on supported security features.

4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).



Technical Specifications

POWER

HP 45 W USB type C	Dimensions 94.0 mm x 40.0 mm x 26.5 mm		5 mm
Straight 1.8 m AC Adapter	Weight	192.5 g +/- 10 g	
		(Not including power cord. Po	ower cord varies by country)
	Input	Input Efficiency	Average Efficiency of 25%, 50%, 75%, 100% load condition with 115Vac/230Vac Spec: 5V: 81.5% 9V: 86.7% 12V: 87.41% 15V: 87.8%
		Input frequency range	47 ~ 63 Hz
		Input AC current	Max. 1.4 A at 90 VAC
	Output	Output power	5V/15W 9V/27W 12V/36W 15V/45W
		DC output	5V / 9V / 12V / 15V
		Hold-up time	5ms at 115 Vac input
		Output current limit	< 5.0A
	Connector	USB Type-C™	
	Environmental Design	Operating temperature	32° to 95° F (0° to 35° C)
		Non-operating (storage) temperature	-4° to 185° F (-20° to 85° C)
		Altitude	0 to 16,400 ft (0 to 5000m)
		Humidity	20% to 95%
		Storage Humidity	10% to 95%
	EMI and Safety Certifications	CE Mark - full compliance with LVD and EMC directives. Worldwide safety standards - IEC60950-1 and/or IEC62368-1, EN60950- and/or EN62368-1, UL60950-1 and/or UL62368-1, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55032 Class B, FCC Class B, CISPR32 Class B, CCC, NOM-001 NYCE. MTBF - over 200,000 hours at 25°C ambient condition.	
HP 45 W Smart AC adapter	Dimensions Weight	3.74 x 1.57 x 1.04 in (9.5 x 0.386 lb (175g) max (Not including power cord. Po	
	Input	90 to 265 VAC	wer cord valles by country,
		Input Efficiency	87.74% at 115Vac and 88.4% at 230Vac
		Input frequency range	47 ~ 63 Hz
		Input AC current	1.4 A at 90 VAC
	Output	Output power	45 W
	-	DC output	19.5 V
		Hold-up time	5ms at 115 Vac input
		Output current limit	<8.0A
		-	



	Connector Environmental Design EMI and Safety Certifications	Operating temperature Non-operating (storage) temperature Altitude Humidity Storage Humidity CE Mark - full compliance w Worldwide safety standard	grounded, mates with interchangeable cords 32° to 95° F (0° to 35° C) -4° to 185° F (-20° to 85° C) 0 to 16,400 ft (0 to 5000m) 20% to 95% 10% to 95% vith LVD and EMC directives. Is - IEC60950-1 and/or IEC62368-1, EN60950-1 50-1 and/or UL62368-1, Class1, SELV;
		Agency approvals - C-UL-U Class B, CISPR32 Class B, C	S, NORDICS, DENAN, EN55032 Class B, FCC
AC Adapter 45 Watt Smart nPFC Standard Barrel 4.5		95.0 x 40.0 x 26.5 mm	
mm Right Angle 1.8 m	Weight	200 g +/- 10 g (Not including power cord. Pc	wer cord varies by country)
2prong	Input	Input Efficiency	87.74% at 115Vac and 88.4% at 230Vac
	-	Input frequency range	47 ~ 63 Hz
		Input AC current	1.4 A at 90 VAC
	Output	Output power	45 W
		DC output	19.5 V
		Hold-up time	5ms at 115 Vac input
		Output current limit	<8.0A
	Connector	C6	
	Environmental Design	Operating temperature	32° to 95° F (0° to 35° C)
		Non-operating (storage) temperature	-4° to 185° F (-20° to 85° C)
		Altitude	0 to 16,400 ft (0 to 5000m)
		Humidity	20% to 95%
		Storage Humidity	10% to 95%
	EMI and Safety Certifications	Worldwide safety standar 1 and/or EN62368-1, UL60 Agency approvals - C-UL-L Class B, CISPR32 Class B, C	with LVD and EMC directives. ds - IEC60950-1 and/or IEC62368-1, EN60950- D950-1 and/or UL62368-1 , Class1, SELV; JS, NORDICS, DENAN, EN55032 Class B, FCC CCC, NOM-001 NYCE. s at 25°C ambient condition.



Technical Specific	ations			
AC Adapter 65 Watt nPFC	Dimensions	90.0 x 51 x 28.5 mm		
Standard USB Type-C	Weight	250 g +/- 10 g		
Straight 1.8 m		(Not including power cord. Po		
	Input	Input Efficiency	81.5% min at 115 Vac/ 230Vac @ 5V/3A 86.7% min at 115 Vac/ 230Vac @ 9V/3A 88% min at 115 Vac/ 230Vac @ 12V/5A 89% min at 115 Vac/ 230Vac @ 15V/4.33A 89% min at 115 Vac/ 230Vac @ 20V/3.25A	
		Input frequency range	47 ~ 63 Hz	
		Input AC current	1.6 A at 90 VAC and maximum load	
	Output	Output power	65 W	
		DC output	5V/9V/12V/15V/20V	
		Hold-up time	5ms at 115 Vac input	
		Output current limit	<8.0A MAXIMUM	
	Connector	USB Type-C™		
	Environmental Design	Operating temperature	32° to 95° F (0° to 35° C)	
		Non-operating (storage) temperature	-4° to 185° F (-20° to 85° C)	
		Altitude	0 to 16,400 ft (0 to 5000m)	
		Humidity	20% to 95%	
		Storage Humidity	10% to 95%	
	and/or EN62368-1, UL60950-1 and/or UL62		Is - IEC60950-1 and/or IEC62368-1, EN60950-1 50-1 and/or UL62368-1 , Class1, SELV; IS, NORDICS, DENAN, EN55032 Class B, FCC Class DM-001 NYCE.	
AC Adapter 65 Watt Smart	Dimensions	102 x 55 x 30 mm		
nPFC EM Barrel 4.5 mm New EM	Weight	250 g +/- 10 g		
4.5 IIIII NEW EM		(Not including power cord. Po		
	Input	Input Efficiency	88.0 % at 115 Vac and 89.0 % at 230Vac	
		Input frequency range	47 ~ 63 Hz	
		Input AC current	1.7 A at 90 Vac	
	Output	Output power	65 W	
		DC output	19.5 V	
		Hold-up time	5ms at 115 Vac input	
		Output current limit	<11.0 A	
	Connector	C6		
	Environmental Design	Operating temperature	32° to 95° F (0° to 35° C)	

temperature Altitude

Humidity

Non-operating (storage) -4° to 185° F (-20° to 85° C)

0 to 16,400 ft (0 to 5000m)

20% to 95%

	EMI and Safety Certifications			
AC Adapter 65 Watt Smart	Dimensions	90.0 x 51 x 28.5 mm		
nPFC Standard Barrel 4.5	Weight	230 g +/- 10 g		
mm Right Angle 1.8 m	-	(Not including power cord. Power cord varies by country)		
	Input	Input Efficiency	88.0 % at 115 Vac and 89.0 % at 230Vac	
		Input frequency range	47 ~ 63 Hz	
		Input AC current	1.7 A at 90 Vac	
	Output	Output power	65 W	
		DC output	19.5 V	
		Hold-up time	5ms at 115 Vac input	
		Output current limit	<11.0 A	
	Connector	4.5mm Barrel Type, 3 pin/grounded, mates with interchangeable core		
	Environmental Design	Operating temperature	32° to 95° F (0° to 35° C)	
		Non-operating (storage) temperature	-4° to 185° F (-20° to 85° C)	
		Altitude	0 to 16,400 ft (0 to 5000m)	
		Humidity	20% to 95%	
		Storage Humidity	10% to 95%	
	EMI and Safety Certifications	CE Mark - full compliance with LVD and EMC directives. Worldwide safety standards - IEC60950-1 and/or IEC62368-1, EN6095 and/or EN62368-1, UL60950-1 and/or UL62368-1, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55032 Class B, FCC Class B, CISPR32 Class B, CCC, NOM-001 NYCE. MTBF - over 200,000 hours at 25°C ambient condition.		

Battery SX 3 Cell 45 Wh Long Life -PL	Dimensions (H x W x L)	184.62 x 85.25 x 6.15 mm	1	
Fast Charge	Weight	0.195 kg Max		
	Cells/Type	3cell Lithium-Ion Polymer cell		
	Energy	Voltage	13.2V / 11.55V (13.2V / 11.4V)	
		Amp-hour capacity	3.9 Ah / 3.75 Ah (3.95 Ah / 3.79 Ah)	
		Watt-hour capacity	45 Wh	
	Tomporature	Operating (Charging)	32° to 113° F (0° to 45° C)	
	Temperature	Operating (Discharging)	14° to 122° F (-10° to 60° C)	
	Optional Travel Battery Available	No		
	Warranty	Based on system offering		



ENVIRONMENTAL DATA

Eco-Label Certifications &	This product has receive	d or is in the process of being c	ertified to the following approvals and may	
declarations	be labeled with one or m	ore of these marks:		
	 EPEAT^D Gold reg status in your co TCO 8.0 China Energy Co 	R® gy Management Program (FEM jistered in the United States. Se puntry. inservation Program (CECP) ironmental Protection Adminis ark	ee http://www.epeat.net for registration	
Sustainable Impact	• 35% post-consumer recycled plastic			
Specifications	-	ated cushions are 100% sustai hion inside box is 100% sustair ns		
System Configuration	-	The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a "Typically Configured Notebook".		
Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz	
Normal Operation (Sort idle)	5.68 W	5.85 W	5.73 W	
Normal Operation (Long idle)	0.81 W	0.83 W	0.79 W	
Sleep	0.81 W	0.83 W	0.79 W	
Off	0.22 W	0.25 W	0.22 W	
	Note: Energy efficiency data lis	ited is for an ENERGY STAR® co	mpliant product if offered within the model	

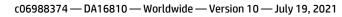


	for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.						
Heat Dissipation*	115VA	C, 60Hz	230VAC	, 50Hz		100VAC, 50Hz	
Normal Operation (Short idle)	19 B	TU/hr	20 BT	U/hr		20 BTU/hr	
Normal Operation (Long idle)	3 B1	ſU/hr	3 BTI	J/hr		3 BTU/hr	
Sleep	3 B1	ſU/hr	3 BTI	J/hr		3 BTU/hr	
Off	1 B1	īU/hr	1 BTI	J/hr		1 BTU/hr	
	*NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.						
Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	Sound Power (L _{WAd} , bels)			Sound Pressure (L _{pAm} , decibels)			
Typically Configured – Idle	2.6			15.4			
Fixed Disk – Random writes	2.6		15.4				
Optical Drive – Sequential reads	4.1		20.7				
Longevity and Upgrading Additional Information	features an period and • Th di	nd/or compor or for up to " his product is rective – 2011	nents contained 5" years after t in compliance v 1/65/EC.	in the spare he end of pro vith the Restr	parts are availab duction. ictions of Hazarc	veral years. Upgradeable le throughout the warranty lous Substances (RoHS)	
	(M • Th Di • Th W • Pl IS	VEEE) Directiv his product is rinking Water his product is ww.epeat.net astics parts w 01043.	re – 2002/96/E0 in compliance v and Toxic Enfo in compliance v t veighing over 2	C. vith California rcement Act o vith the IEEE 5 grams used	a Proposition 65 of 1986). 1680 (EPEAT) sta	ical and Electronic Equipment (State of California; Safe Indard at the Gold level, see re marked per ISO11469 and of at end of life.	
Packaging Materials	Externa:	PAPER/Cor	rugated			256g	
	Internal:	ernal: PAPER/Molded pulp PLASTIC/Polyethylene low density				171 g 14 g	



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	PLASTIC/polypropylene	3
	The plastic packaging material contains at least 0% recycled	-
	The corrugated paper packaging materials contains at least	
RoHS Compliance	HP Inc. complies fully with materials regulations. We were an the restrictions in the European Union (EU) Restriction of Haz to our products worldwide through the HP GSE. HP has contri legislation in Europe, as well as China, India, and Vietnam.	nong the first companies to extend ardous Substances (RoHS) Directive
	We believe the RoHS directive and similar laws play an impor elimination of substances of concern. We have supported the including PVC, BFRs, and certain phthalates—in future RoHS and electronics products.	e inclusion of additional substances—
	We met our voluntary objective to achieve worldwide complia requirements for virtually all relevant products by July 2013, scope of the commitment to include further restricted substa evolve.	, and we will continue to extend the
	To obtain a copy of the HP RoHS Compliance Statement, see	HP RoHS position statement.
Material Usage	This product does not contain any of the following substance to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/s	
	 Asbestos Certain Azo Colorants Certain Brominated Flame Retardants – may not be Cadmium Chlorinated Hydrocarbons Chlorinated Paraffins Bis(2-Ethylhexyl) phthalate (DEHP) Benzyl butyl phthalate (BBP) Dibutyl phthalate (DBP) Diisobutyl phthalate (DIBP) Formaldehyde Halogenated Diphenyl Methanes Lead carbonates and sulfates Lead and Lead compounds Mercuric Oxide Batteries Nickel – finishes must not be used on the external su handled or carried by the user. Ozone Depleting Substances Polybrominated Biphenyl Ethers (PBBEs) Polybrominated Biphenyl Oxides (PBBOs) Polychlorinated Terphenyls (PCT) Polyvinyl Chloride (PVC) – except for wires and cable been voluntarily removed from most applications. 	urface designed to be frequently
	 Radioactive Substances Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin O 	xide (TBTO)



Packaging Usage	 HP follows these guidelines to decrease the environmental impact of product packaging: Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. Eliminate the use of ozone-depleting substances (ODS) in packaging materials. Design packaging materials for ease of disassembly. Maximize the use of post-consumer recycled content materials in packaging materials. Use readily recyclable packaging materials such as paper and corrugated materials. Reduce size and weight of packages to improve transportation fuel efficiency. Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life Management and Recycling	HP offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.
	The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.
HP, Inc. Corporate	For more information about HP's commitment to the environment:
Environmental	
Information	Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html
	Eco-label certifications
	http://www8.hp.com/us/en/hp-information/environment/ecolabels.html
	ISO 14001 certificates:
	http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842
	and
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf
footnotes	 Percentage of ocean-bound plastic contained in each component varies by product Recycled plastic content percentage is based on the definition set in the IEEE 1680.1- 2018 standard.
	 External power supplies, WWAN modules, power cords, cables and peripherals excluded. 100% outer box packaging and corrugated cushions made from sustainably sourced certified and recycled fibers.
	 Fiber cushions made from 100% recycled wood fiber and organic materials. Plastic cushions are made from >90% recycled plastic.

COUNTRY OF ORIGIN

China



Options and Accessories (sold separately and availability may vary by country)

Туре	Description	Part #
Cases	HP Essential Top Load Case	H2W17AA
	HP Essential Backpack (up to 15.6")	H1D24AA
Docking	HP USB-C Mini Dock	1PM64AA
	HP Thunderbolt Dock 120W G2	2UK37AA
	HP TB Dock G2 w/ Combo Cable	3TR87AA
	HP TB Dock 120W G2 w/Audio	3YE87AA
	HP TB Dock 120W G2 cable	3XB94AA
	HP TB Dock G2 combo cable	3XB96AA
	HP TB Dock 120W G2 Cable	3XB94AA
	HP TB Dock G2 Combo Cable	3XB96AA
	HP TB Dock G2 Audio Module	3AQ21AA
	HP USB-C/A Universal Dock G2	5TW13AA
	HP USB-C Dock G5	5TW10AA
Input/Output	HP Comfort Grip Wireless Mouse	H2L63AA
	HP 3-Button USB Laser Mouse	H4B81AA
	HP USB Travel Mouse	G1K28AA
	HP Ultra Mobile Wireless Mouse	H6F25AA
	HP USB Fingerprint Mouse	4TS44AA
	HP USB-C to DP	N9K78AA
	HP USB-C to USB-A Hub	Z6A00AA
	HP Elite USB-C Multi Port Hub	4WX89AA
	HP Pro Pen	8JU62AA
	HP USB-C to RJ45 Adapter	V7W66AA
Power	HP 45W Smart AC Adapter 4.5mm	H6Y88AA
	HP 65W Smart AC Adapter 4.5mm	H6Y89AA
	HP 45W LC USB-C Power Adapter	1MZ01AA
	HP 65W LC USB-C Power Adapter	TBD
	USB-C NB Power Bank	1TZ86AA
	HP Essential Power Bank	3TB55AA
Storage	HP External USB Optical Drive	F2B56AA
Memory	HP 4GB DDR4 3200 Memory	286H5AA
	HP 8GB DDR4 3200 Memory	286H8AA
	HP 16GB DDR4 3200 Memory	286J1AA



Options and Accessories (sold separately and availability may vary by country)

Security

HP Sure Key Cable Lock HP Nano Keyed Cable Lock

6UW42AA 1AJ39AA



Date of change: Version History:		Update:	Description of change:		
February 10, 2021	V1 to V2		Processor specs and Environmental Data		
March 9, 2021	V2 to V3	Removed	USB-C to RJ45 Adapter		
March 17, 2021	V3 to V4	Updated	Environmental Data		
March 19, 2021	V4 to V5	Updated	Processor section		
April 20, 2021	V5 to V6	Updated	Memory Section and Input/ Output Section Updated		
May 6, 2021	V6 to V7	Updated	TPM 2.0/Added HP Smart Support		
May 27, 2021	V7 to V8	Updated	HP Pro Security Edition to HP Wolf Pro Security Edition		
June 17, 2021	V8 to V9	Add	Select Models for Micro SD Card Reader in Overview section		
July 19, 2021	V9 to V10	Updated	Networking WLAN; Power section and At a Glance section		

Summary of Changes

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